



# Material Composition Declaration

## EPC2121

Company Name	Efficient Power Conversion (EPC)	Issue Date:	8/8/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	1.1 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)		
Chip	Silicon	7440-21-3	0.9344	85.1910	88.8257	851910
	Silicon oxide	7631-86-9	0.0060	0.5477		5477
	Silicon nitride	12033-89-5	0.0018	0.1616		1616
	Gallium nitride	25617-97-4	0.0047	0.4297		4297
	Aluminum	7429-90-5	0.0084	0.7634		7634
	Aluminum nitride	24304-00-5	0.0009	0.0818		818
	Titanium	7440-32-6	0.0002	0.0163		163
	Titanium nitride	25583-20-4	0.0080	0.7283		7283
	Copper	7440-50-8	0.0001	0.0127		127
	Tungsten	7440-33-7	0.0013	0.1188		1188
Polyimide		0.0085	0.7745	7745		
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0080	0.0877	80
	Copper	7440-50-8	0.0009	0.0797		797
Solder Bump	Copper	7440-50-8	0.0087	0.7965	11.0866	7965
	Nickel	7440-02-0	0.0052	0.4751		4751
	Tin	7440-31-5	0.1057	9.6383		96383
	Silver	7440-22-4	0.0019	0.1767		1767
Sum in total:			1.0968	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.